



RF LDMOS Wideband Integrated Power Amplifier

The MW4IC001N wideband integrated circuit is designed for use as a distortion signature device in analog predistortion systems. It uses Freescale's newest High Voltage (26 to 28 Volts) LDMOS IC technology. Its wideband On Chip design makes it usable from 800 MHz to 2170 MHz. The linearity performances cover all modulations for cellular applications: GSM EDGE, TDMA, CDMA and W-CDMA.

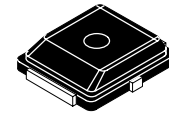
- Typical CW Performance at 2170 MHz, 28 Volts, $I_{DQ} = 12$ mA
 Output Power — 900 mW PEP
 Power Gain — 13 dB
 Efficiency — 38%

Features

- High Gain, High Efficiency and High Linearity
- Designed for Maximum Gain and Insertion Phase Flatness
- Excellent Thermal Stability
- Characterized with Series Equivalent Large-Signal Impedance Parameters
- N Suffix Indicates Lead-Free Terminations. RoHS Compliant.
- In Tape and Reel. R4 Suffix = 100 Units per 12 mm, 7 inch Reel.

MW4IC001NR4

**800-2170 MHz, 900 mW, 28 V
 W-CDMA
 RF LDMOS WIDEBAND
 INTEGRATED POWER AMPLIFIER**



**CASE 466-03, STYLE 1
 PLD-1.5
 PLASTIC**

Table 1. Maximum Ratings

| Rating | Symbol | Value | Unit |
|--|-----------|---------------|--------------------------|
| Drain-Source Voltage | V_{DSS} | - 0.5, +65 | Vdc |
| Gate-Source Voltage | V_{GS} | - 0.5, +15 | Vdc |
| Total Device Dissipation @ $T_C = 25^\circ\text{C}$ Derate above 25°C | P_D | 4.58 0.037 | W W/ $^\circ\text{C}$ |
| Storage Temperature Range | T_{stg} | - 65 to +150 | $^\circ\text{C}$ |
| Operating Junction Temperature | T_J | 150 | $^\circ\text{C}$ |

Table 2. Thermal Characteristics

| Characteristic | Symbol | Value | Unit |
|---|-----------------|-------|---------------------------|
| Thermal Resistance, Junction to Case @ 85°C | $R_{\theta JC}$ | 27.3 | $^\circ\text{C}/\text{W}$ |

Table 3. ESD Protection Characteristics

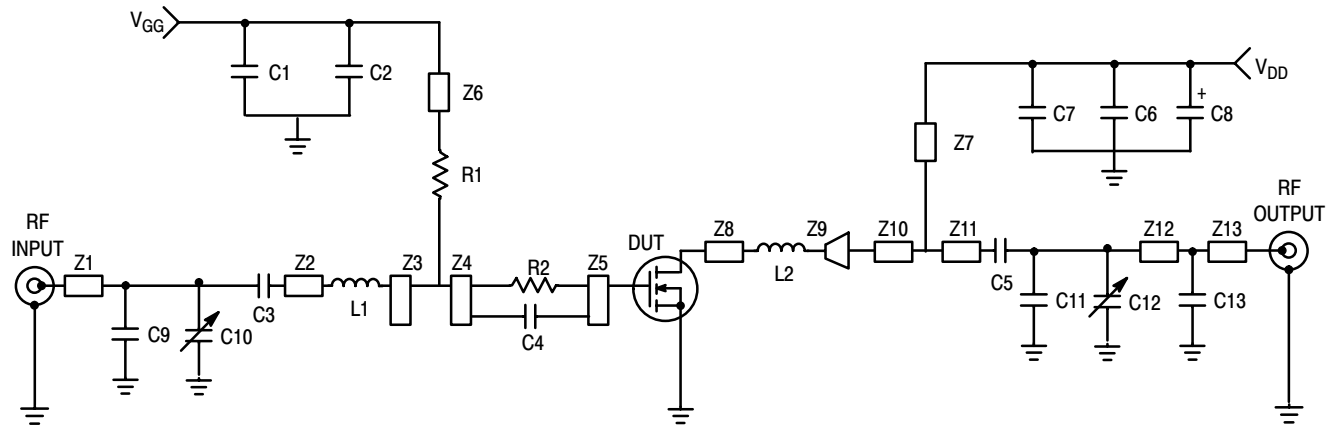
| Test Conditions | Class |
|---------------------|--------------|
| Human Body Model | 0 (Minimum) |
| Machine Model | M1 (Minimum) |
| Charge Device Model | C2 (Minimum) |

Table 4. Moisture Sensitivity Level

| Test Methodology | Rating | Package Peak Temperature | Unit |
|---------------------------------------|--------|--------------------------|------------------|
| Per JESD 22-A113, IPC/JEDEC J-STD-020 | 3 | 260 | $^\circ\text{C}$ |

Table 5. Electrical Characteristics ($T_C = 25^\circ\text{C}$ unless otherwise noted)

| Characteristic | Symbol | Min | Typ | Max | Unit |
|---|--------------|-----|------|-----|-----------------|
| Off Characteristics | | | | | |
| Zero Gate Voltage Drain Current ($V_{DS} = 65\text{ Vdc}$, $V_{GS} = 0\text{ Vdc}$) | I_{DSS} | — | — | 10 | μAdc |
| Zero Gate Voltage Drain Current ($V_{DS} = 28\text{ Vdc}$, $V_{GS} = 0\text{ Vdc}$) | I_{DSS} | — | — | 10 | μAdc |
| Gate-Source Leakage Current ($V_{GS} = 5\text{ Vdc}$, $V_{DS} = 0\text{ Vdc}$) | I_{GSS} | — | — | 1 | μAdc |
| On Characteristics | | | | | |
| Gate Threshold Voltage ($V_{DS} = 10\text{ V}$, $I_D = 50\ \mu\text{A}$) | $V_{GS(th)}$ | 2 | 3 | 5 | Vdc |
| Gate Quiescent Voltage ($V_{DS} = 28\text{ V}$, $I_D = 10\text{ mA}$) | $V_{GS(Q)}$ | 2 | 3.7 | 5 | Vdc |
| Drain-Source On-Voltage ($V_{GS} = 10\text{ V}$, $I_D = 0.05\text{ A}$) | $V_{DS(on)}$ | — | 0.48 | 0.9 | Vdc |
| Forward Transconductance ($V_{DS} = 10\text{ V}$, $I_D = 0.1\text{ A}$) | g_{fs} | — | 0.05 | — | S |
| Dynamic Characteristics | | | | | |
| Output Capacitance ($V_{DS} = 28\text{ Vdc} \pm 30\text{ mV(rms)ac}$ @ 1 MHz, $V_{GS} = 0\text{ Vdc}$) | C_{oss} | — | 45 | — | pF |
| Reverse Transfer Capacitance ($V_{DS} = 28\text{ Vdc} \pm 30\text{ mV(rms)ac}$ @ 1 MHz, $V_{GS} = 0\text{ Vdc}$) | C_{rss} | — | 0.62 | — | pF |
| Functional Tests (In Freescale Test Fixture, 50 ohm system) | | | | | |
| Two-Tone Common Source Amplifier Power Gain ($V_{DD} = 28\text{ Vdc}$, $P_{out} = 0.9\text{ W PEP}$, $I_{DQ} = 12\text{ mA}$, $f = 2170\text{ MHz}$, Tone Spacing = 100 kHz) | G_{ps} | — | 13 | — | dB |
| Two-Tone Drain Efficiency ($V_{DD} = 28\text{ Vdc}$, $P_{out} = 0.9\text{ W PEP}$, $I_{DQ} = 12\text{ mA}$, $f = 2170\text{ MHz}$, Tone Spacing = 100 kHz) | η_D | — | 29 | — | % |
| Third Order Intermodulation Distortion ($V_{DD} = 28\text{ Vdc}$, $P_{out} = 0.9\text{ W PEP}$, $I_{DQ} = 12\text{ mA}$, $f = 2170\text{ MHz}$, Tone Spacing = 100 kHz) | IMD | — | -28 | — | dBc |
| Input Return Loss ($V_{DD} = 28\text{ Vdc}$, $P_{out} = 0.9\text{ W PEP}$, $I_{DQ} = 12\text{ mA}$, $f = 2170\text{ MHz}$, Tone Spacing = 100 kHz) | IRL | — | -18 | — | dB |
| Output Power, 1 dB Compression Point, CW ($V_{DD} = 28\text{ Vdc}$, $I_{DQ} = 12\text{ mA}$, $f = 2170\text{ MHz}$) | P1dB | — | 0.85 | — | W |
| Common-Source Amplifier Power Gain ($V_{DD} = 28\text{ Vdc}$, $P_{out} = 0.9\text{ W CW}$, $I_{DQ} = 12\text{ mA}$, $f = 2170\text{ MHz}$) | G_{ps} | 12 | 13 | — | dB |
| Drain Efficiency ($V_{DD} = 28\text{ Vdc}$, $P_{out} = 0.9\text{ W CW}$, $I_{DQ} = 12\text{ mA}$, $f = 2170\text{ MHz}$) | η_D | 35 | 38 | — | % |
| Input Return Loss ($V_{DD} = 28\text{ Vdc}$, $P_{out} = 0.9\text{ W CW}$, $I_{DQ} = 12\text{ mA}$, $f = 2170\text{ MHz}$) | IRL | -10 | -16 | — | dB |

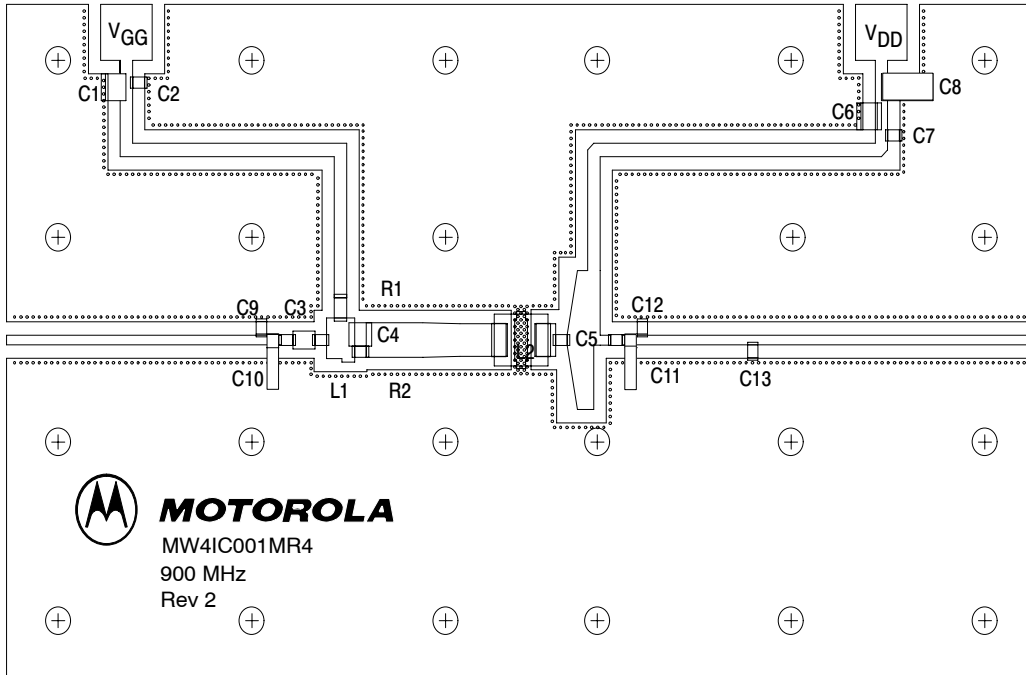


| | | | |
|--------|----------------------------|-----|---|
| Z1 | 1.331" x 0.044" Microstrip | Z9 | 0.062" x 0.044" to 0.615" Taper |
| Z2 | 0.126" x 0.076" Microstrip | Z10 | 0.082" x 0.615" Microstrip |
| Z3 | 0.065" x 0.175" Microstrip | Z11 | 0.075" x 0.044" Microstrip |
| Z4 | 0.065" x 0.195" Microstrip | Z12 | 0.625" x 0.044" Microstrip |
| Z5 | 0.680" x 0.145" Microstrip | Z13 | 1.375" x 0.044" Microstrip |
| Z6, Z7 | 1.915" x 0.055" Microstrip | PCB | Rogers RO4350, 0.020", $\epsilon_r = 3.5$ |
| Z8 | 0.120" x 0.141" Microstrip | | |

Figure 1. MW4IC001NR4 900 MHz Test Circuit Schematic

Table 6. MW4IC001NR4 900 MHz Test Circuit Component Designations and Values

| Part | Description | Part Number | Manufacturer |
|----------------|--|------------------|--------------|
| C1, C6 | 0.1 μ F, 100 V Chip Capacitors | C1210C104K5RACTR | Kemet |
| C2, C3, C5, C7 | 43 pF, 500 V Chip Capacitors | 100B430JP500X | ATC |
| C4 | 12 pF, 500 V Chip Capacitor | 100B120JP500X | ATC |
| C8 | 22 μ F, 35 V Tantalum Chip Capacitor | T491X226K035AS | Kemet |
| C9 | 4.7 pF, 500 V Chip Capacitor | 100B4R7CP500X | ATC |
| C10, C11 | 0.6-4.5 pF, 500 V Variable Capacitors | 27271SL | Johanson |
| C12 | 2.7 pF, 500 V Chip Capacitor | 100B2R7CP500X | ATC |
| C13 | 3.3 pF, 500 V Chip Capacitor | 100B3R3CP500X | ATC |
| L1 | 5.6 nH Chip Inductor | 0805 Series | AVX |
| L2 | 10 nH Chip Inductor | 1008 Series | ATC |
| R1 | 100 Ω Chip Resistor | CRCW12061001F100 | Dale |
| R2 | 20 Ω Chip Resistor | CRCW120620R0F100 | Dale |



Freescale has begun the transition of marking Printed Circuit Boards (PCBs) with the Freescale Semiconductor signature/logo. PCBs may have either Motorola or Freescale markings during the transition period. These changes will have no impact on form, fit or function of the current product.

Figure 2. MW4IC001NR4 900 MHz Test Circuit Component Layout

TYPICAL CHARACTERISTICS - 900 MHz

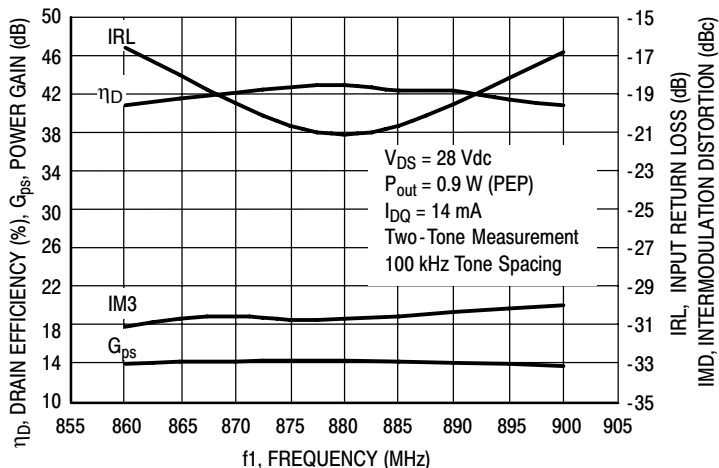


Figure 3. Two-Tone Performance versus Frequency

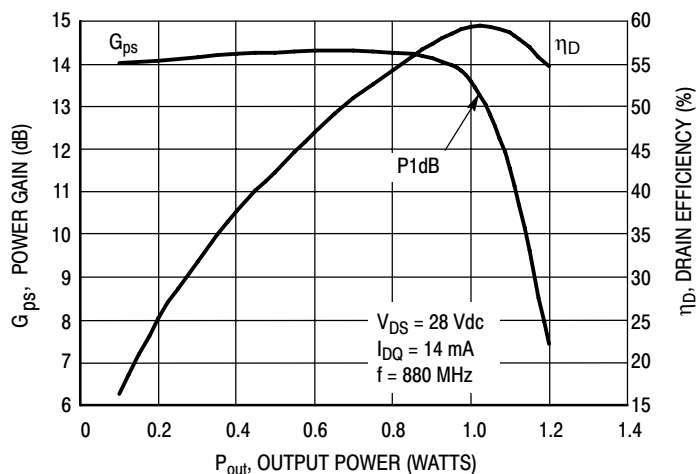


Figure 4. CW Performance versus Output Power

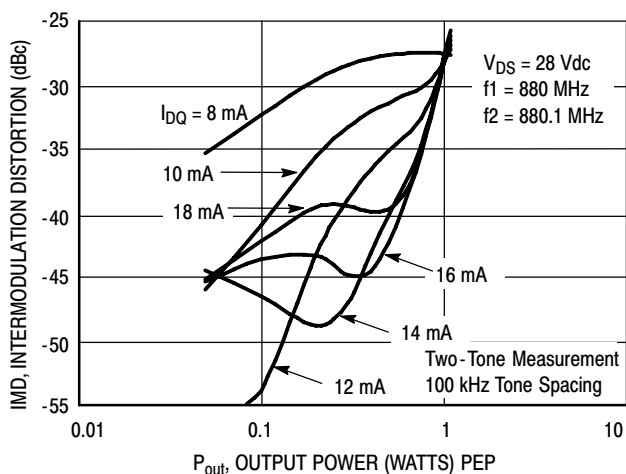


Figure 5. Intermodulation Distortion versus Output Power

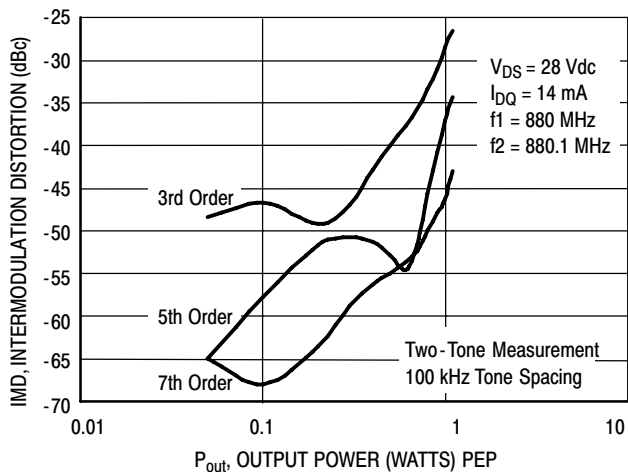


Figure 6. Intermodulation Distortion Products versus Output Power

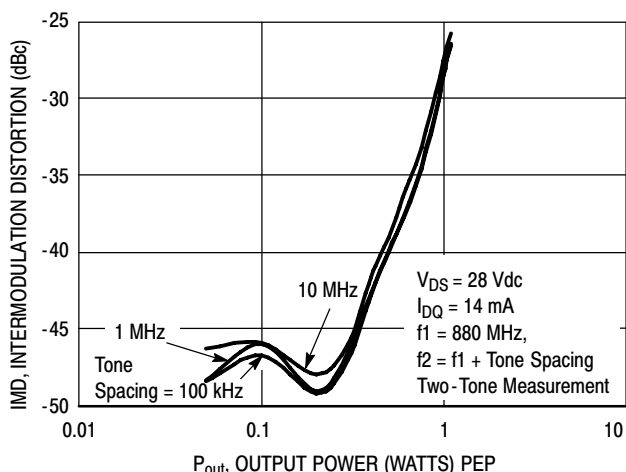
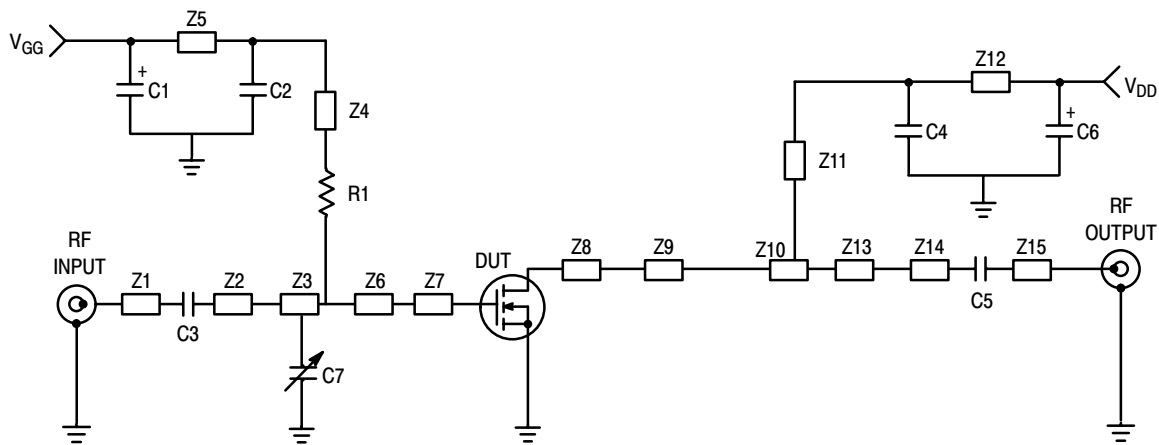


Figure 7. Third Order Intermodulation Distortion versus Output Power

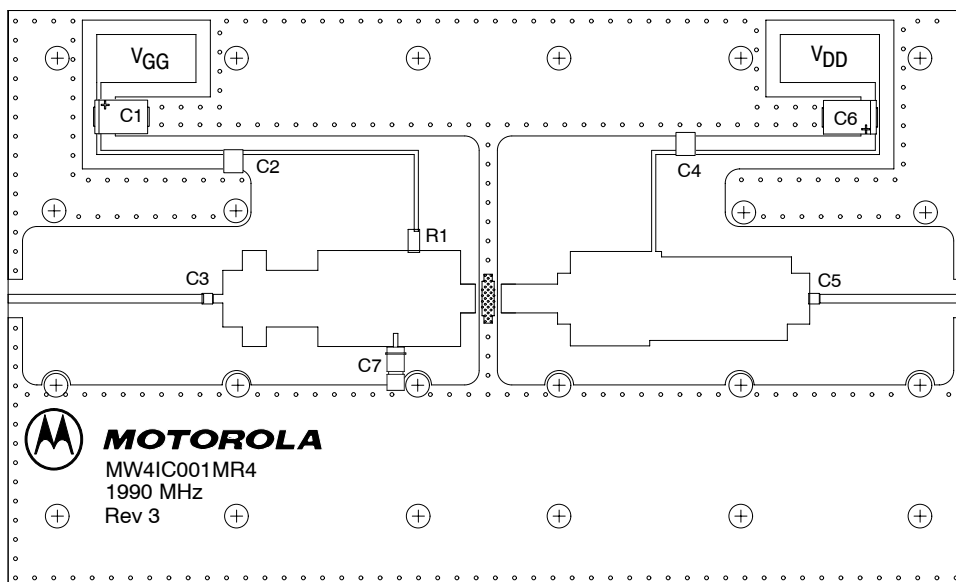


| | | | |
|----|----------------------------|-----|---|
| Z1 | 1.018" x 0.044" Microstrip | Z9 | 0.067" x 0.264" Microstrip |
| Z2 | 0.495" x 0.296" Microstrip | Z10 | 0.457" x 0.492" Microstrip |
| Z3 | 0.893" x 0.500" Microstrip | Z11 | 0.719" x 0.022" Microstrip |
| Z4 | 1.340" x 0.022" Microstrip | Z12 | 1.149" x 0.022" Microstrip |
| Z5 | 0.912" x 0.022" Microstrip | Z13 | 0.677" x 0.434" Microstrip |
| Z6 | 0.241" x 0.500" Microstrip | Z14 | 0.095" x 0.264" Microstrip |
| Z7 | 0.076" x 0.150" Microstrip | Z15 | 0.772" x 0.044" Microstrip |
| Z8 | 0.294" x 0.150" Microstrip | PCB | Rogers RO4350, 0.020", $\epsilon_r = 3.5$ |

Figure 8. MW4IC001NR4 1990 MHz Test Circuit Schematic

Table 7. MW4IC001NR4 1990 MHz Test Circuit Component Designations and Values

| Part | Description | Part Number | Manufacturer |
|--------|--------------------------------------|------------------|--------------|
| C1, C6 | 22 μ F, 35 V Tantalum Capacitors | T491X226K035AS | Kemet |
| C2, C4 | 10 pF, 500 V Chip Capacitors | 100B100JCA500X | ATC |
| C3, C5 | 10 pF, 500 V Chip Capacitor | 600S100JW | ATC |
| C7 | 0.6-4.5 pF, 500 V Variable Capacitor | 27271SL | Johanson |
| R1 | 1 k Ω Chip Resistor | CRCW12061021F100 | Dale |



Freescale has begun the transition of marking Printed Circuit Boards (PCBs) with the Freescale Semiconductor signature/logo. PCBs may have either Motorola or Freescale markings during the transition period. These changes will have no impact on form, fit or function of the current product.

Figure 9. MW4IC001NR4 1990 MHz Test Circuit Component Layout

TYPICAL CHARACTERISTICS - 1990 MHz

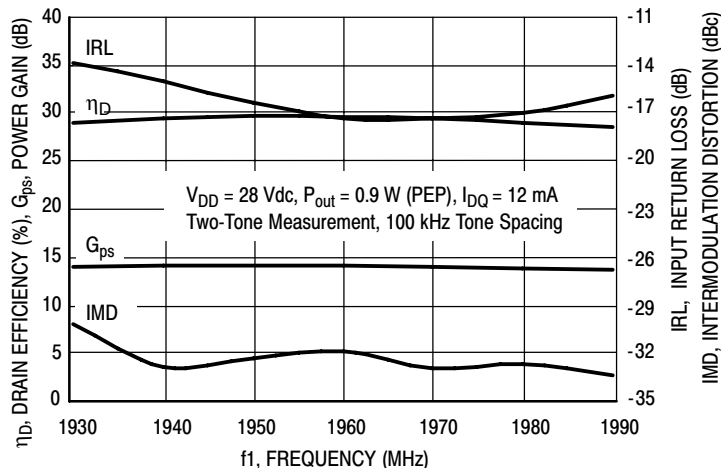


Figure 10. Two-Tone Performance versus Frequency

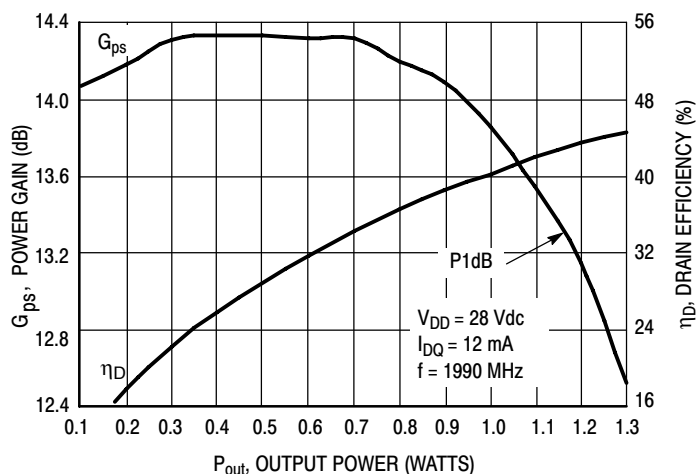


Figure 11. CW Performance versus Output Power

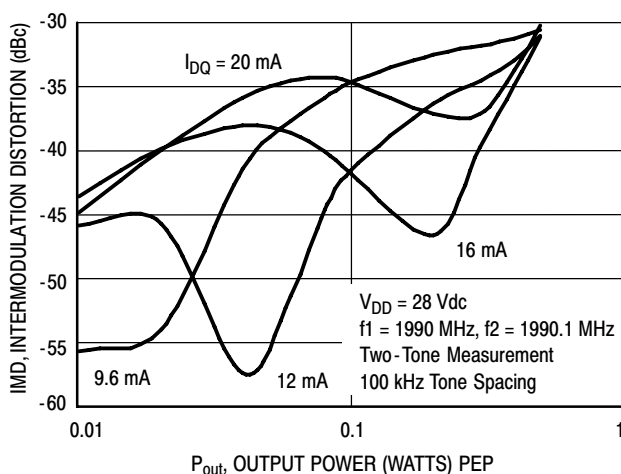


Figure 12. Intermodulation Distortion versus Output Power

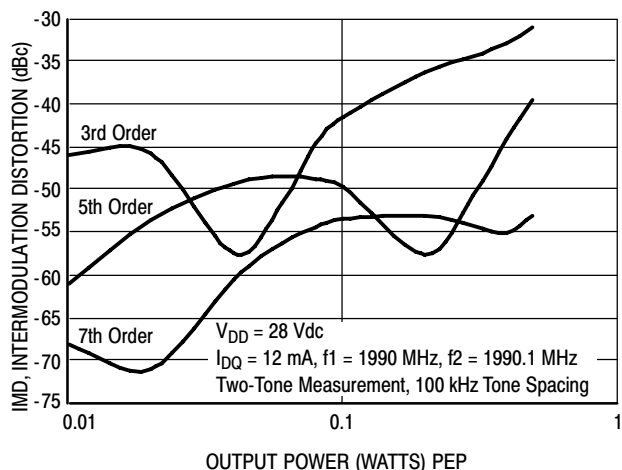


Figure 13. Intermodulation Distortion Products versus Output Power

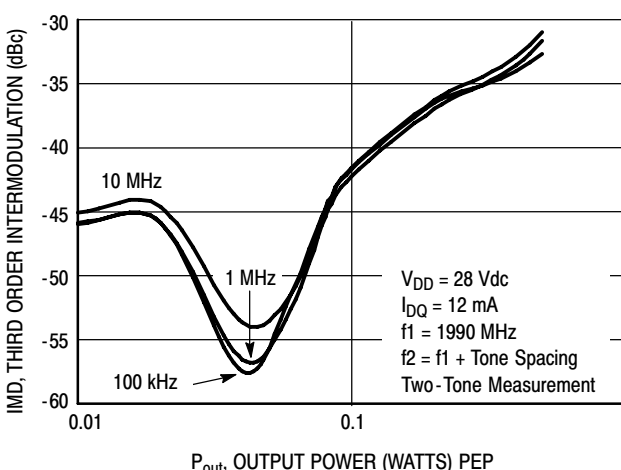
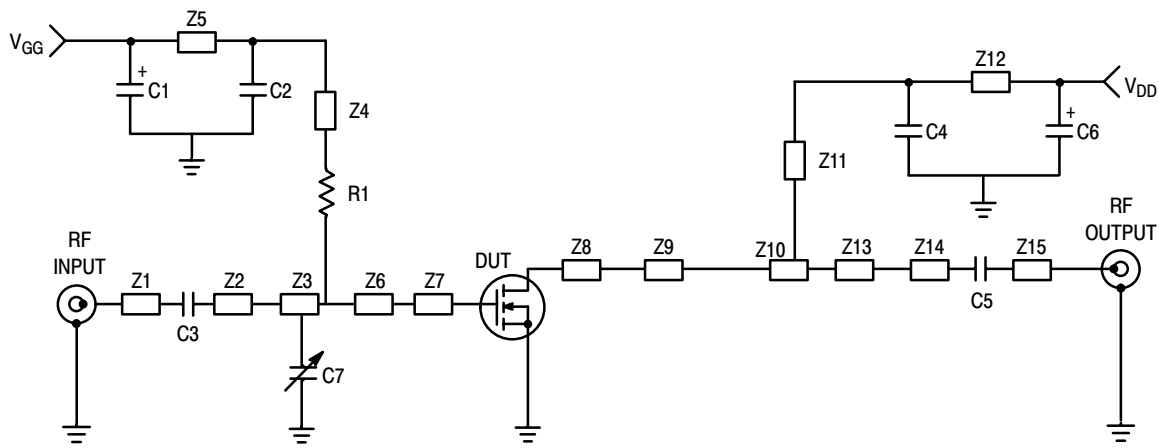


Figure 14. Third Order Intermodulation Distortion versus Output Power

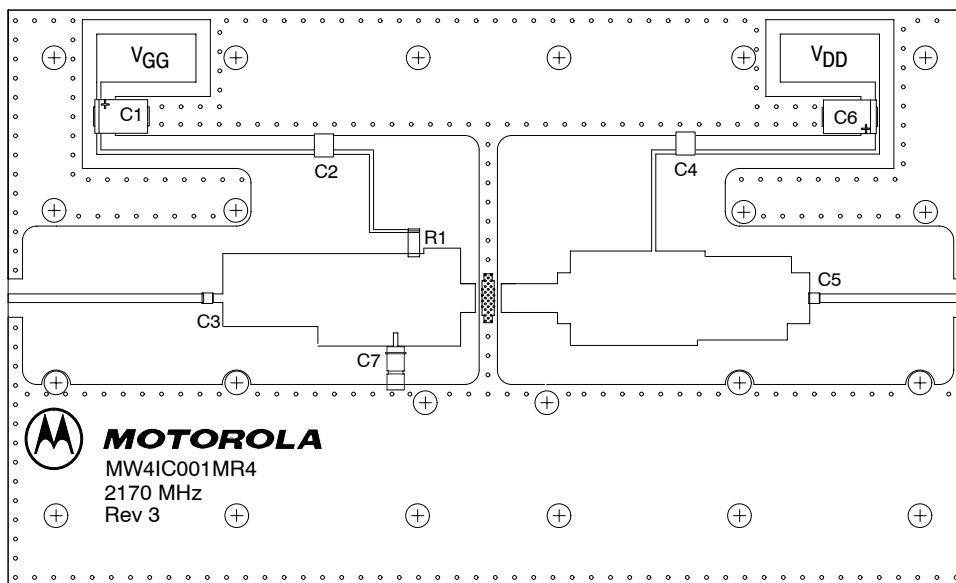


| | | | |
|----|----------------------------|-----|---|
| Z1 | 1.267" x 0.044" Microstrip | Z9 | 0.106" x 0.344" Microstrip |
| Z2 | 0.058" x 0.044" Microstrip | Z10 | 0.783" x 0.500" Microstrip |
| Z3 | 0.758" x 0.256" Microstrip | Z11 | 0.847" x 0.022" Microstrip |
| Z4 | 1.073" x 0.022" Microstrip | Z12 | 1.055" x 0.022" Microstrip |
| Z5 | 1.361" x 0.022" Microstrip | Z13 | 0.291" x 0.387" Microstrip |
| Z6 | 0.205" x 0.332" Microstrip | Z14 | 0.050" x 0.287" Microstrip |
| Z7 | 0.109" x 0.150" Microstrip | Z15 | 0.950" x 0.044" Microstrip |
| Z8 | 0.210" x 0.150" Microstrip | PCB | Rogers RO4350, 0.020", $\epsilon_r = 3.5$ |

Figure 15. MW4IC001NR4 2170 MHz Test Circuit Schematic

Table 8. MW4IC001NR4 2170 MHz Test Circuit Component Designations and Values

| Part | Description | Part Number | Manufacturer |
|--------|--------------------------------------|------------------|--------------|
| C1, C6 | 22 μ F, 35 V Tantalum Capacitors | T491X226K035AS | Kemet |
| C2, C4 | 10 pF, 500 V Chip Capacitors | 100B100JCA500X | ATC |
| C3, C5 | 10 pF, 500 V Chip Capacitor | 600S100JW | ATC |
| C7 | 0.6-4.5 pF, 500 V Variable Capacitor | 27271SL | Johanson |
| R1 | 1 k Ω Chip Resistor | CRCW12061021F100 | Dale |



Freescale has begun the transition of marking Printed Circuit Boards (PCBs) with the Freescale Semiconductor signature/logo. PCBs may have either Motorola or Freescale markings during the transition period. These changes will have no impact on form, fit or function of the current product.

Figure 16. MW4IC001NR4 2170 MHz Test Circuit Component Layout

TYPICAL CHARACTERISTICS - 2170 MHz

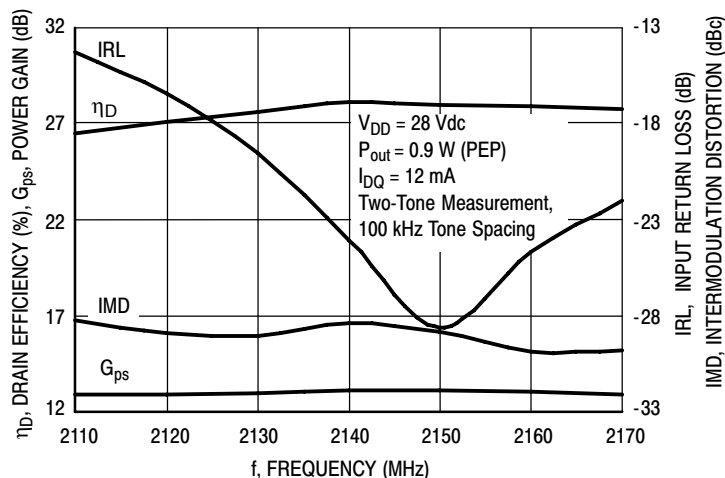


Figure 17. Two-Tone Performance versus Frequency

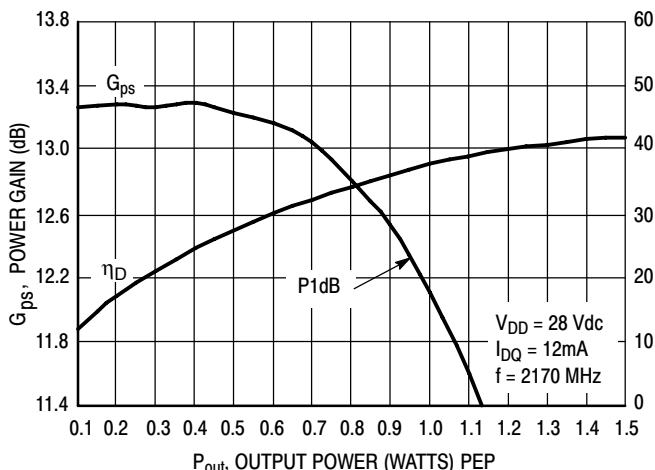


Figure 18. CW Performance versus Output Power

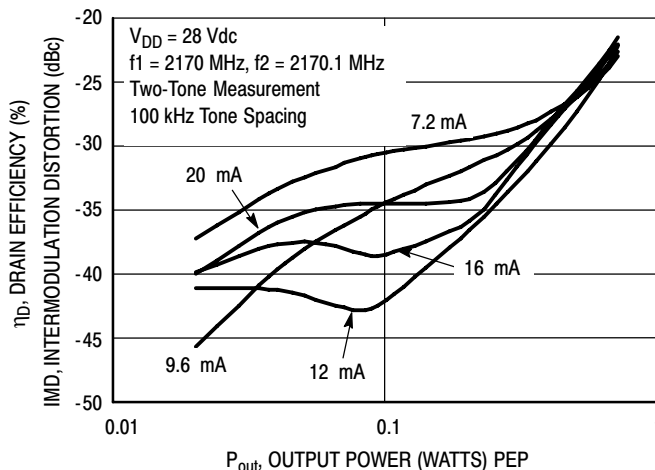


Figure 19. Intermodulation Distortion versus Output Power

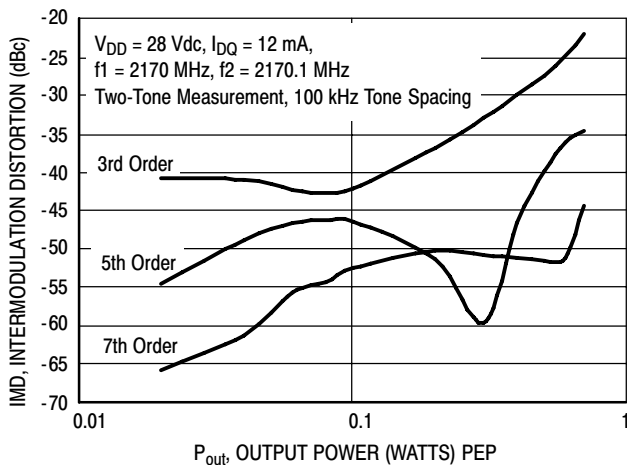


Figure 20. Intermodulation Distortion Products versus Output Power

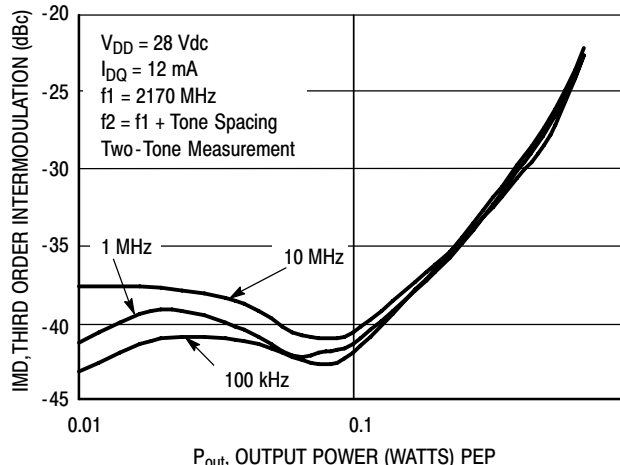
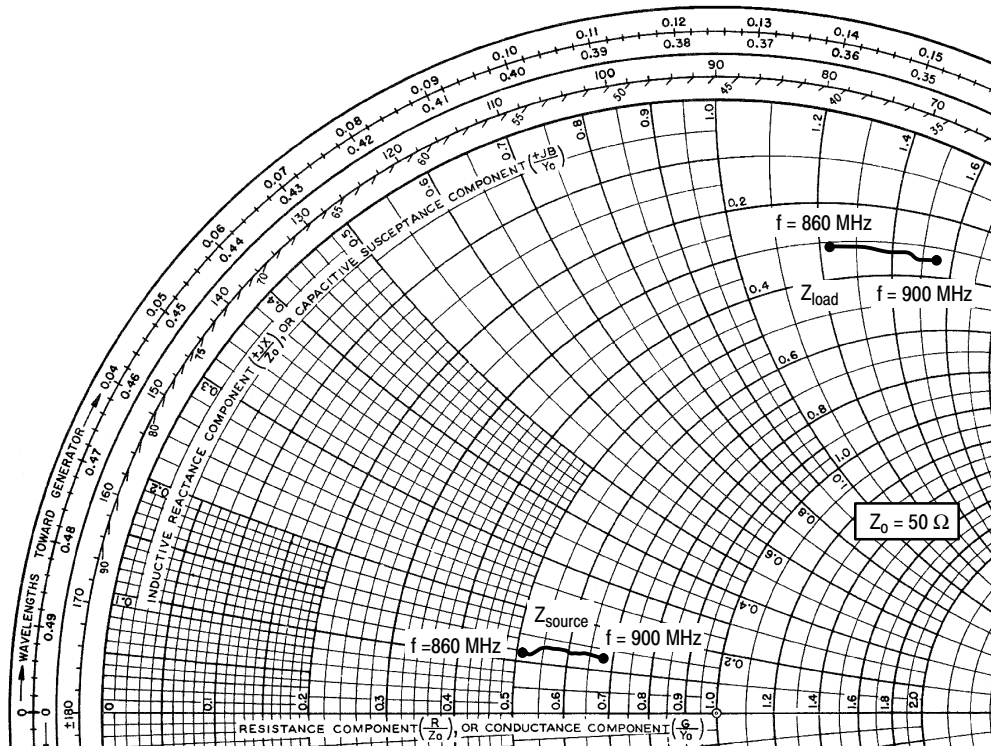


Figure 21. Third Order Intermodulation Distortion versus Output Power



$V_{DD} = 28\text{ V}$, $I_{DQ} = 14\text{ mA}$, $P_{out} = 0.9\text{ W PEP}$

| f MHz | Z_{source} Ω | Z_{load} Ω |
|----------|--------------------------|------------------------|
| 860 | $27.853 + j5.908$ | $15.492 + j63.669$ |
| 865 | $28.617 + j6.078$ | $15.592 + j68.687$ |
| 870 | $29.458 + j6.285$ | $15.788 + j69.799$ |
| 875 | $30.306 + j6.422$ | $15.835 + j70.863$ |
| 880 | $31.223 + j6.567$ | $15.975 + j71.920$ |
| 885 | $32.194 + j6.660$ | $16.094 + j73.091$ |
| 890 | $33.228 + j6.656$ | $16.286 + j74.159$ |
| 895 | $34.293 + j6.624$ | $16.344 + j75.236$ |
| 900 | $35.424 + j6.508$ | $16.628 + j76.283$ |

Z_{source} = Test circuit impedance as measured from gate to ground.

Z_{load} = Test circuit impedance as measured from drain to ground.

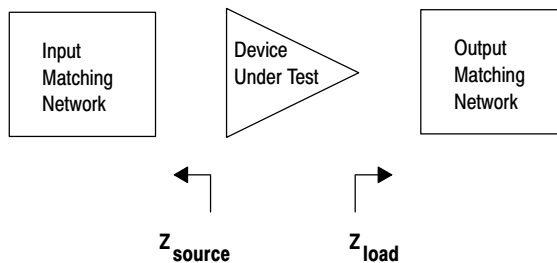
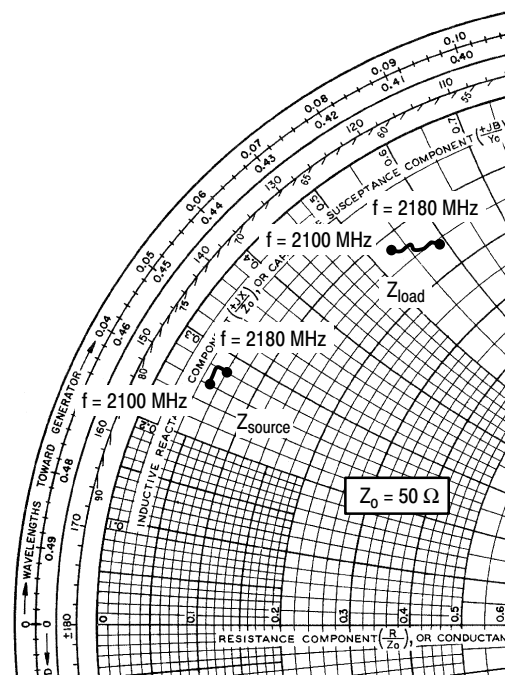
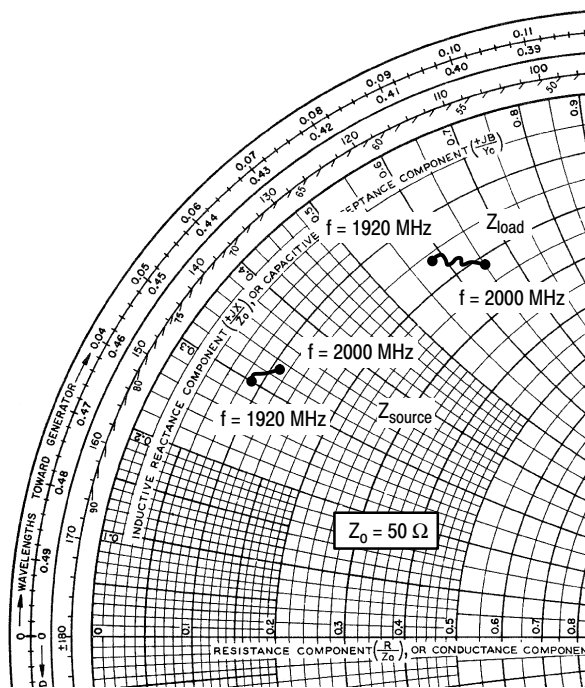


Figure 22. Series Equivalent Source and Load Impedance

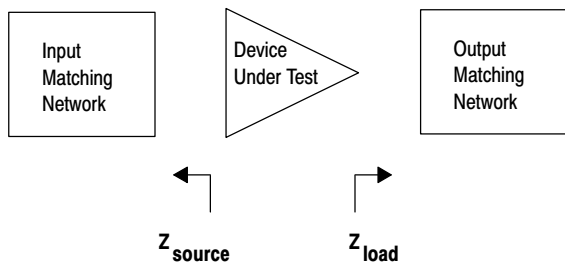


$V_{DD} = 28\text{ V}$, $I_{DQ} = 12\text{ mA}$, $P_{out} = 0.9\text{ W PEP}$

| f MHz | Z_{source} Ω | Z_{load} Ω |
|-------|-----------------------|---------------------|
| 1920 | $4.238 + j15.142$ | $7.764 + j28.829$ |
| 1930 | $4.322 + j15.362$ | $8.056 + j29.352$ |
| 1940 | $4.490 + j15.466$ | $8.436 + j29.727$ |
| 1950 | $4.605 + j15.711$ | $8.809 + j30.249$ |
| 1960 | $4.752 + j15.904$ | $9.183 + j30.763$ |
| 1970 | $4.905 + j16.050$ | $9.598 + j31.213$ |
| 1980 | $5.071 + j16.236$ | $10.030 + j31.690$ |
| 1990 | $5.262 + j16.446$ | $10.546 + j32.237$ |
| 2000 | $5.487 + j16.632$ | $11.054 + j32.726$ |

Z_{source} = Test circuit impedance as measured from gate to ground.

Z_{load} = Test circuit impedance as measured from drain to ground.



$V_{DD} = 28\text{ V}$, $I_{DQ} = 12\text{ mA}$, $P_{out} = 0.9\text{ W PEP}$

| f MHz | Z_{source} Ω | Z_{load} Ω |
|-------|-----------------------|---------------------|
| 2100 | $2.667 + j12.903$ | $5.892 + j26.374$ |
| 2110 | $2.671 + j13.070$ | $6.092 + j26.739$ |
| 2120 | $2.664 + j13.224$ | $6.281 + j27.094$ |
| 2130 | $2.694 + j13.431$ | $6.540 + j27.510$ |
| 2140 | $2.703 + j13.511$ | $6.748 + j27.795$ |
| 2150 | $2.702 + j13.700$ | $6.996 + j28.182$ |
| 2160 | $2.745 + j13.952$ | $7.300 + j28.678$ |
| 2170 | $2.754 + j14.026$ | $7.562 + j28.987$ |
| 2180 | $2.784 + j14.206$ | $7.862 + j29.411$ |

Z_{source} = Test circuit impedance as measured from gate to ground.

Z_{load} = Test circuit impedance as measured from drain to ground.

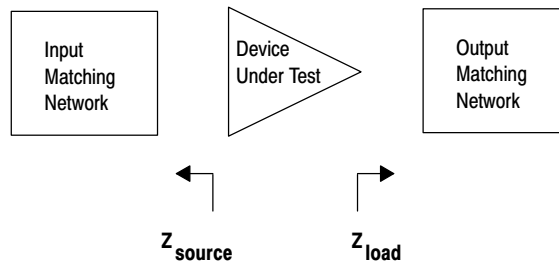


Figure 23. Series Equivalent Source and Load Impedance

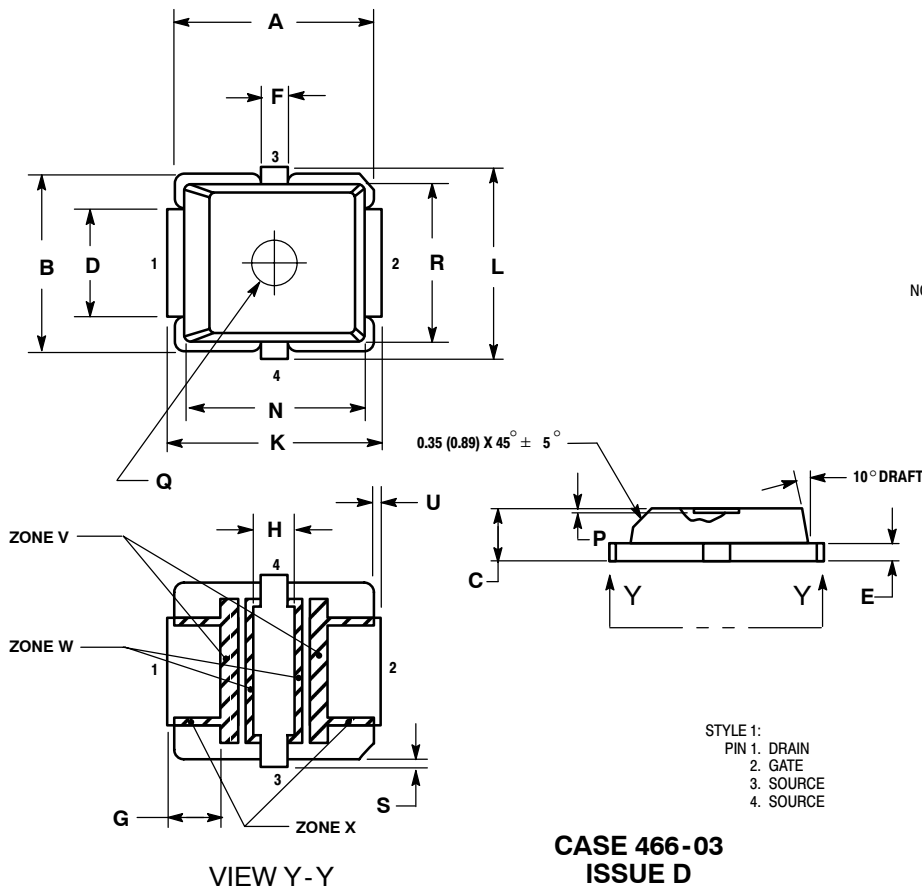
NOTES



NOTES

NOTES

PACKAGE DIMENSIONS



- NOTES:
1. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1984.
 2. CONTROLLING DIMENSION: INCH
 3. RESIN BLEED/FLASH ALLOWABLE IN ZONE V, W, AND X.

| DIM | INCHES | | MILLIMETERS | |
|--------|--------|-------|-------------|------|
| | MIN | MAX | MIN | MAX |
| A | 0.255 | 0.265 | 6.48 | 6.73 |
| B | 0.225 | 0.235 | 5.72 | 5.97 |
| C | 0.065 | 0.072 | 1.65 | 1.83 |
| D | 0.130 | 0.150 | 3.30 | 3.81 |
| E | 0.021 | 0.026 | 0.53 | 0.66 |
| F | 0.026 | 0.044 | 0.66 | 1.12 |
| G | 0.050 | 0.070 | 1.27 | 1.78 |
| H | 0.045 | 0.063 | 1.14 | 1.60 |
| J | 0.160 | 0.180 | 4.06 | 4.57 |
| K | 0.273 | 0.285 | 6.93 | 7.24 |
| L | 0.245 | 0.255 | 6.22 | 6.48 |
| N | 0.230 | 0.240 | 5.84 | 6.10 |
| P | 0.000 | 0.008 | 0.00 | 0.20 |
| Q | 0.055 | 0.063 | 1.40 | 1.60 |
| R | 0.200 | 0.210 | 5.08 | 5.33 |
| S | 0.006 | 0.012 | 0.15 | 0.31 |
| U | 0.006 | 0.012 | 0.15 | 0.31 |
| ZONE V | 0.000 | 0.021 | 0.00 | 0.53 |
| ZONE W | 0.000 | 0.010 | 0.00 | 0.25 |
| ZONE X | 0.000 | 0.010 | 0.00 | 0.25 |

**CASE 466-03
 ISSUE D
 PLD-1.5
 PLASTIC**

How to Reach Us:

Home Page:
www.freescale.com

E-mail:
support@freescale.com

USA/Europe or Locations Not Listed:
Freescale Semiconductor
Technical Information Center, CH370
1300 N. Alma School Road
Chandler, Arizona 85224
+1-800-521-6274 or +1-480-768-2130
support@freescale.com

Europe, Middle East, and Africa:
Freescale Halbleiter Deutschland GmbH
Technical Information Center
Schatzbogen 7
81829 Muenchen, Germany
+44 1296 380 456 (English)
+46 8 52200080 (English)
+49 89 92103 559 (German)
+33 1 69 35 48 48 (French)
support@freescale.com

Japan:
Freescale Semiconductor Japan Ltd.
Headquarters
ARCO Tower 15F
1-8-1, Shimo-Meguro, Meguro-ku,
Tokyo 153-0064
Japan
0120 191014 or +81 3 5437 9125
support.japan@freescale.com

Asia/Pacific:
Freescale Semiconductor Hong Kong Ltd.
Technical Information Center
2 Dai King Street
Tai Po Industrial Estate
Tai Po, N.T., Hong Kong
+800 2666 8080
support.asia@freescale.com

For Literature Requests Only:
Freescale Semiconductor Literature Distribution Center
P.O. Box 5405
Denver, Colorado 80217
1-800-441-2447 or 303-675-2140
Fax: 303-675-2150
LDCForFreescaleSemiconductor@hibbertgroup.com

RoHS-compliant and/or Pb-free versions of Freescale products have the functionality and electrical characteristics of their non-RoHS-compliant and/or non-Pb-free counterparts. For further information, see <http://www.freescale.com> or contact your Freescale sales representative.

For information on Freescale's Environmental Products program, go to <http://www.freescale.com/epp>.

Information in this document is provided solely to enable system and software implementers to use Freescale Semiconductor products. There are no express or implied copyright licenses granted hereunder to design or fabricate any integrated circuits or integrated circuits based on the information in this document.

Freescale Semiconductor reserves the right to make changes without further notice to any products herein. Freescale Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does Freescale Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation consequential or incidental damages. "Typical" parameters that may be provided in Freescale Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals", must be validated for each customer application by customer's technical experts. Freescale Semiconductor does not convey any license under its patent rights nor the rights of others. Freescale Semiconductor products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the Freescale Semiconductor product could create a situation where personal injury or death may occur. Should Buyer purchase or use Freescale Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold Freescale Semiconductor and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that Freescale Semiconductor was negligent regarding the design or manufacture of the part.

Freescale™ and the Freescale logo are trademarks of Freescale Semiconductor, Inc. All other product or service names are the property of their respective owners.
© Freescale Semiconductor, Inc. 2006. All rights reserved.

RoHS-compliant and/or Pb-free versions of Freescale products have the functionality and electrical characteristics of their non-RoHS-compliant and/or non-Pb-free counterparts. For further information, see <http://www.freescale.com> or contact your Freescale sales representative.

For information on Freescale's Environmental Products program, go to <http://www.freescale.com/epp>.

